PATENT
Attorney Docket No.: COOL-01800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Group Art Unit: 3753
Kenneth Goodson et al.	Examiner:
Serial No.: 10/698,304	**TRANSMITTAL LETTER**
Filed: October 30, 2003	162 N. Wolfe Road Sunnyvale, CA 94086 (408) 530-9700
For: **METHOD AND APPARATUS FOR ACHIEVING TEMPERATURE UNIFORMITY AND HOT SPOT COOLING IN A HEAT PRODUCING DEVICE**	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

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You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #60113); (EFS ID #60115); (EFS ID #60117) and (EFS ID #60119) filed on April 29, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

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CERTIFICATE OF MAILING (37 CFR§ 1.8(a))

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HAVERSTOCK & OWENS LLP.

Date: 4-30-04 By:

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INFORMATION DISCLOSURE STATEMENT

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #60113); (EFS ID #60115); (EFS ID #60117) and (EFS ID #60119). Applicants have become aware of the following printed publication which may be material to the examination of this application:

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This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

By: _____
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)		Applicants: Kenneth Goodson et al.	
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